

4K I²C™ Serial EEPROM

Device Selection Table

Part Number	Vcc Range	Max Clock Frequency	Temp. Range
24AA044	1.7V-5.5V	1 MHz ⁽¹⁾	I, E

Note 1: 400 kHz for $1.8V \leq V_{CC} < 2.2V$
100 kHz for $V_{CC} < 1.8V$

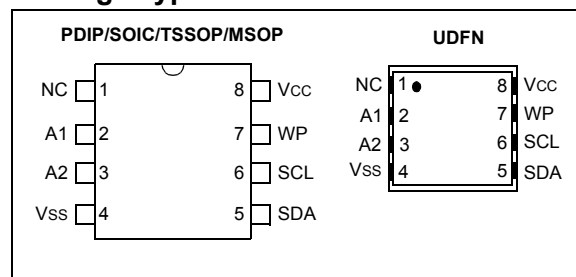
Features:

- Single Supply with Operation from 1.7V to 5.5V
- Low-Power CMOS Technology:
 - Read current 400 μ A, max
 - Standby current 1 μ A, max at 85°C
- 2-Wire Serial Interface, I²C™ Compatible
- Cascadable up to Four Devices
- Schmitt Trigger Inputs for Noise Suppression
- Output Slope Control to Eliminate Ground Bounce
- 1 MHz, 400 kHz, and 100 kHz Clock Compatibility
- Page Write Time 5 ms Maximum
- Self-timed Erase/Write Cycle
- 16-Byte Page Write Buffer
- Hardware Write-Protect
- ESD Protection >4,000V
- More than 1 Million Erase/Write Cycles
- Data Retention >200 Years
- Factory Programming Available
- Packages include 8-lead PDIP, SOIC, TSSOP, UDFN and MSOP
- RoHS Compliant
- Temperature Ranges:
 - Industrial (I): -40°C to +85°C
 - Automotive (E): -40°C to +125°C

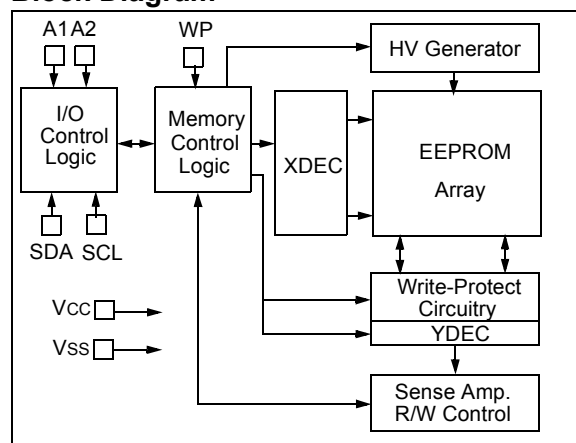
Description:

The Microchip Technology Inc. 24AA044 is a 4 Kbit Serial Electrically Erasable PROM with a voltage range of 1.7V to 5.5V. The device is organized as two blocks of 256 x 8-bit memory with a 2-wire serial interface. Low-current design permits operation with standby and active currents of only 1 μ A and 400 μ A, respectively. The device has a page write capability for up to 16 bytes of data. Functional address lines allow the connection of up to four 24AA044 devices on the same bus for up to 16K bits of contiguous EEPROM memory. The device is available in the standard 8-pin PDIP, 8-pin SOIC (3.90 mm), TSSOP, 2x3 UDFN and MSOP packages.

Package Types



Block Diagram



24AA044

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings^(†)

V _{CC}	6.5V
All inputs and outputs w.r.t. V _{SS}	-0.3V to 6.5V
Storage temperature	-65°C to +150°C
Ambient temperature with power applied	-40°C to +125°C
ESD protection on all pins	≥ 4 kV

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TABLE 1-1: DC SPECIFICATIONS

DC CHARACTERISTICS			Industrial (I): TA = -40°C to +85°C, V _{CC} = +1.7V to +5.5V Automotive (E): TA = -40°C to +125°C, V _{CC} = +1.7V to +5.5V			
Param. No.	Symbol	Characteristic	Min.	Max.	Units	Conditions
	—	A1, A2, SCL, SDA and WP pins	—	—	—	—
D1	V _{IH}	High-level input voltage	0.7 V _{CC}	V _{CC} + 0.5	V	—
D2	V _{IL}	Low-level input voltage	—	0.3 V _{CC} 0.2 V _{CC}	V V	V _{CC} ≥ 2.5V V _{CC} < 2.5V
D3	V _{HYS}	Hysteresis of Schmitt Trigger inputs	0.05 V _{CC}	—	V	(Note)
D4	V _{OL}	Low-level output voltage	—	0.40	V	I _{OL} = 3.0 mA, V _{CC} = 2.5V
D5	I _{LI}	Input leakage current	—	±1	μA	V _{IN} = V _{SS} or V _{CC}
D6	I _{LO}	Output leakage current	—	±1	μA	V _{OUT} = V _{SS} or V _{CC}
D7	C _{IN} , C _{OUT}	Pin capacitance (all inputs/outputs)	—	10	pF	V _{CC} = 5.5V (Note) TA = 25°C, F _{CLK} = 1 MHz
D8	I _{CC} write	Operating current	—	3	mA	V _{CC} = 5.5V
D9	I _{CC} read		—	400	μA	V _{CC} = 5.5V, SCL = 1 MHz
D10	I _{CCS}	Standby current	—	1	μA	Industrial Automotive SDA, SCL = V _{CC} A1, A2, WP = V _{SS}
			—	5	μA	

Note: This parameter is periodically sampled and not 100% tested.

TABLE 1-2: AC CHARACTERISTICS

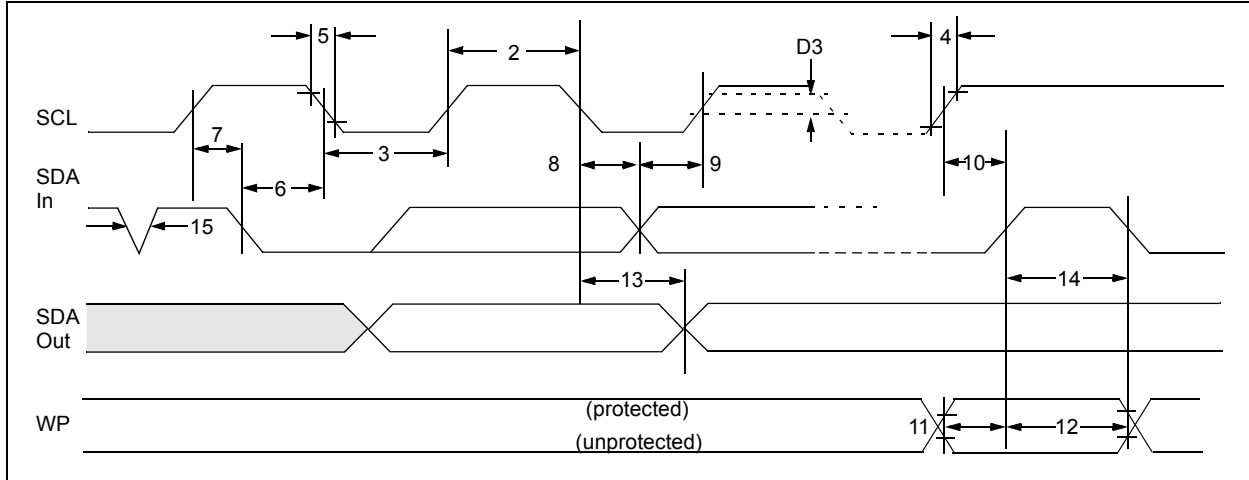
AC CHARACTERISTICS			Industrial (I): TA = -40°C to +85°C, VCC = +1.7V to +5.5V Automotive (E): TA = -40°C to +125°C, VCC = +1.7V to +5.5V			
Param. No.	Symbol	Characteristic	Min.	Max.	Units	Conditions
1	FCLK	Clock frequency	— — —	100 400 1000	kHz	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
2	THIGH	Clock high time	4000 600 500	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
3	TLOW	Clock low time	4700 1300 500	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
4	TR	SDA and SCL rise time (Note 1)	— — —	1000 300 300	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
5	TF	SDA and SCL fall time (Note 1)	— — —	300 300 100	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
6	THD:STA	Start condition hold time	4000 600 250	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
7	TSU:STA	Start condition setup time	4700 600 250	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
8	THD:DAT	Data input hold time	0	—	ns	(Note 2)
9	TSU:DAT	Data input setup time	250 100 100	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
10	TSU:STO	Stop condition setup time	4000 600 250	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
11	TSU:WP	WP setup time	4000 600 600	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
12	THD:WP	WP hold time	4700 1300 1300	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
13	TAA	Output valid from clock (Note 2)	— — —	3500 900 400	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
14	TBUF	Bus free time: Time the bus must be free before a new transmission can start	4700 1300 500	— — —	ns	1.7V ≤ VCC < 1.8V 1.8V ≤ VCC < 2.2V 2.2V ≤ VCC < 5.5V
15	TSP	Input filter spike suppression (SDA and SCL pins)	—	50	ns	(Note 1)
16	TWC	Write cycle time (byte or page)	—	5	ms	—
17	—	Endurance	1M	—	cycles	Page mode, 25°C, VCC = 5.5V (Note 3)

Note 1: Not 100% tested.

Note 2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 200 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

Note 3: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's web site at www.microchip.com.

FIGURE 1-1: BUS TIMING DATA



2.0 PIN DESCRIPTIONS

Pin Function Table

Name	PDIP	SOIC	TSSOP	UDFN	MSOP	Description
NC	1	1	1	1	1	Not Connected
A1	2	2	2	2	2	Chip Address Input
A2	3	3	3	3	3	Chip Address Input
VSS	4	4	4	4	4	Ground
SDA	5	5	5	5	5	Serial Address/Data I/O
SCL	6	6	6	6	6	Serial Clock
WP	7	7	7	7	7	Write-Protect Input
VCC	8	8	8	8	8	+1.7 to 5.5V Power Supply

2.1 Serial Data (SDA)

SDA is a bidirectional pin used to transfer addresses and data into and out of the device. It is an open-drain terminal; therefore, the SDA bus requires a pull-up resistor to Vcc (typical 10 k Ω for 100 kHz, 2 k Ω for 400 kHz and 1 MHz).

For normal data transfer, SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the Start and Stop conditions.

2.2 Serial Clock (SCL)

The SCL input is used to synchronize the data transfer from and to the device.

2.3 Chip Address Inputs (A1, A2)

The levels on the A1 and A2 inputs are compared with the corresponding bits in the slave address. The chip is selected if the compare is true.

Up to four 24AA044 devices may be connected to the same bus by using different Chip Select bit combinations. These inputs must be connected to either Vcc or Vss.

2.4 Write-Protect (WP)

WP is the hardware write-protect pin. It must be tied to Vcc or Vss. If tied to Vcc, hardware write protection is enabled. If WP is tied to Vss, the hardware write protection is disabled.

2.5 Noise Protection

The 24AA044 employs a Vcc threshold detector circuit which disables the internal erase/write logic if the Vcc is below 1.35V at nominal conditions.

The SCL and SDA inputs have Schmitt Trigger and filter circuits which suppress noise spikes to assure proper device operation, even on a noisy bus.

3.0 FUNCTIONAL DESCRIPTION

The 24AA044 supports a bidirectional, 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as transmitter, while a device receiving data is defined as receiver. The bus has to be controlled by a master device that generates the Serial Clock (SCL), controls the bus access and generates the Start and Stop conditions, while the 24AA044 works as slave. Both master and slave can operate as transmitter or receiver, but the master device determines which mode is activated.

4.0 BUS CHARACTERISTICS

The following **bus protocol** has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is high. Changes in the data line while the clock line is high will be interpreted as a Start or Stop condition.

Accordingly, the following bus conditions have been defined (Figure 4-1).

4.1 Bus Not Busy (A)

Both data and clock lines remain high.

4.2 Start Data Transfer (B)

A high-to-low transition of the SDA line while the clock (SCL) is high determines a Start condition. All commands must be preceded by a Start condition.

4.3 Stop Data Transfer (C)

A low-to-high transition of the SDA line while the clock (SCL) is high determines a Stop condition. All operations must be ended with a Stop condition.

4.4 Data Valid (D)

The state of the data line represents valid data when, after a Start condition, the data line is stable for the duration of the high period of the clock signal.

The data on the line must be changed during the low period of the clock signal. There is one bit of data per clock pulse.

Each data transfer is initiated with a Start condition and terminated with a Stop condition. The number of the data bytes transferred between the Start and Stop conditions is determined by the master device and is, theoretically, unlimited (though only the last sixteen will be stored when performing a write operation). When an overwrite does occur, it will replace data in a first-in first-out fashion.

4.5 Acknowledge

Each receiving device, when addressed, is required to generate an acknowledge after the reception of each byte. The master device must generate an extra clock pulse, which is associated with this Acknowledge bit.

Note: The 24AA044 does not generate any Acknowledge bits if an internal programming cycle is in progress.

The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable-low during the high period of the acknowledge-related clock pulse. Of course, setup and hold times must be taken into account. A master must signal an end of data to the slave by not generating an Acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave must leave the data line high to enable the master to generate the Stop condition (Figure 4-2).

FIGURE 4-1: DATA TRANSFER SEQUENCE ON THE SERIAL BUS CHARACTERISTICS



FIGURE 4-2: ACKNOWLEDGE TIMING



5.0 DEVICE ADDRESSING

A control byte is the first byte received following the Start condition from the master device (Figure 5-1). The control byte consists of a 4-bit control code. For the 24AA044, this is set as '1010' binary for read and write operations. The next two bits of the control byte are the Chip Select bits (A2, A1). The Chip Select bits allow the use of up to four 24AA044 devices on the same bus and are used to select which device is accessed. The Chip Select bits in the control byte must correspond to the logic levels on the corresponding A2 and A1 pins for the device to respond. These bits are in effect the two Most Significant bits of the array address.

The next bit of the control byte is the block select bit (B0). This bit acts as the A8 address bit for accessing the entire array.

The last bit of the control byte defines the operation to be performed. When set to a one, a read operation is selected. When set to a zero, a write operation is selected. Following the Start condition, the 24AA044 monitors the SDA bus checking the control byte being transmitted. Upon receiving a '1010' code and appropriate Chip Select bits, the slave device outputs an Acknowledge signal on the SDA line. Depending on the state of the R/W bit, the 24AA044 will select a read or write operation.

FIGURE 5-1: CONTROL BYTE FORMAT



5.1 Contiguous Addressing Across Multiple Devices

The Chip Select bits A2 and A1 can be used to expand the contiguous address space for up to 16K bits by adding up to four 24AA044 devices on the same bus. In this case, software can use A1 of the control byte as address bit A9, and A2 as address bit A10. It is not possible to sequentially read across device boundaries.

6.0 WRITE OPERATIONS

6.1 Byte Write

Following the Start signal from the master, the device code (4 bits), the Chip Select bits (2 bits), the block select bit (1 bit), and the R/W bit (which is a logic-low) is placed onto the bus by the master transmitter. The device will acknowledge this control byte during the ninth clock pulse. The next byte transmitted by the master is the array address and will be written into the Address Pointer of the 24AA044. After receiving another Acknowledge signal from the 24AA044, the master device will transmit the data byte to be written into the addressed memory location. The 24AA044 acknowledges again and the master generates a Stop condition. This initiates the internal write cycle and, during this time, the 24AA044 will not generate Acknowledge signals (Figure 6-1). If an attempt is made to write to the protected portion of the array when the hardware write protection has been enabled, the device will acknowledge the command, but no data will be written.

6.2 Page Write

The write control byte, array address and the first data byte are transmitted to the 24AA044 in the same way as in a byte write. However, instead of generating a Stop condition, the master transmits up to 15 additional data bytes to the 24AA044, which are temporarily stored in the on-chip page buffer and will be written into the memory once the master has transmitted a Stop condition. Upon receipt of each byte, the four lower-order Address Pointer bits are internally incremented by one.

The higher-order five bits of the array address remain constant. If the master should transmit more than 16 bytes prior to generating the Stop condition, the address counter will roll over and the previously

received data will be overwritten. As with the byte-write operation, once the Stop condition is received, an internal write cycle will begin (Figure 6-2). If an attempt is made to write to the protected portion of the array when the hardware write protection has been enabled, the device will acknowledge the command, but no data will be written.

Note: When doing a write of less than 16 bytes, the data in the rest of the page is refreshed along with the data bytes being written. This will force the entire page to endure a write cycle. For this reason, endurance is specified per page.

Note: Page write operations are limited to writing bytes within a single physical page, **regardless** of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size') and end at addresses that are integer multiples of [page size - 1]. If a Page Write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page, as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

6.3 Write Protection

The WP pin must be tied to VCC or VSS. If tied to VCC, the entire array will be write-protected. If the WP pin is tied to VSS, write operations to all address locations are allowed.

FIGURE 6-1: BYTE WRITE



FIGURE 6-2: PAGE WRITE



7.0 ACKNOWLEDGE POLLING

Since the device will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (this feature can be used to maximize bus throughput). Once the Stop condition for a Write command has been issued from the master, the device initiates the internally-timed write cycle, with ACK polling being initiated immediately. This involves the master sending a Start condition followed by the control byte for a Write command ($R/\overline{W} = 0$). If the device is still busy with the write cycle, no ACK will be returned. If no ACK is returned, the Start bit and control byte must be re-sent. If the cycle is complete, the device will return the ACK and the master can then proceed with the next Read or Write command. See [Figure 7-1](#) for a flow diagram of this operation.

FIGURE 7-1: ACKNOWLEDGE POLLING FLOW



8.0 READ OPERATIONS

Read operations are initiated in the same way as write operations, with the exception that the R/W bit of the slave address is set to '1'. There are three basic types of read operations: current address read, random read and sequential read.

8.1 Current Address Read

The 24AA044 contains an address counter that maintains the address of the last data byte accessed, internally incremented by one. Therefore, if the previous read access was to address n , the next current address read operation would access data from address $n + 1$. Upon receipt of the slave address with the R/W bit set to '1', the 24AA044 issues an acknowledge and transmits the 8-bit data value. The master will not acknowledge the transfer, but does generate a Stop condition and the 24AA044 discontinues transmission (Figure 8-1).

8.2 Random Read

Random read operations allow the master to access any memory location in a random manner. To perform this type of read operation, the array address must first be set. This is accomplished by sending the array address to the 24AA044 as part of a write operation. Once the array address is sent, the master generates a Start condition following the acknowledge. This terminates the write operation, but not before the internal Address Pointer is set. The master then issues the control byte again, but with the R/W bit set to a '1'. The 24AA044 will then issue an acknowledge and transmits the 8-bit data value. The master will not acknowledge the transfer but does generate a Stop condition and the 24AA044 discontinues transmission (Figure 8-2). After this command, the internal address counter will point to the address location following the one that was just read.

8.3 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the 24AA044 transmits the first data byte, the master issues an acknowledge (as opposed to a Stop condition in a random read). This directs the 24AA044 to transmit the next sequentially-addressed 8-bit value (Figure 8-3).

To provide sequential reads, the 24AA044 contains an internal Address Pointer that is incremented by one upon completion of each operation. This Address Pointer allows the entire memory contents to be serially read during one operation. The internal Address Pointer will automatically roll over from address 1FFh to address 000h.

FIGURE 8-1: CURRENT ADDRESS READ

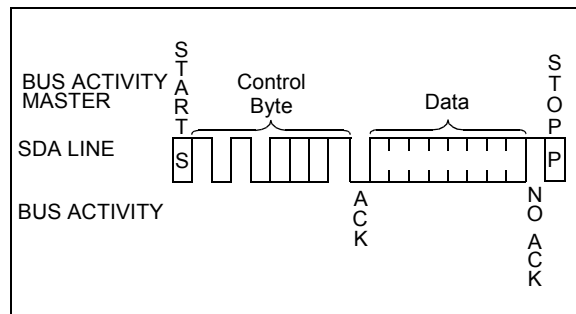


FIGURE 8-2: RANDOM READ

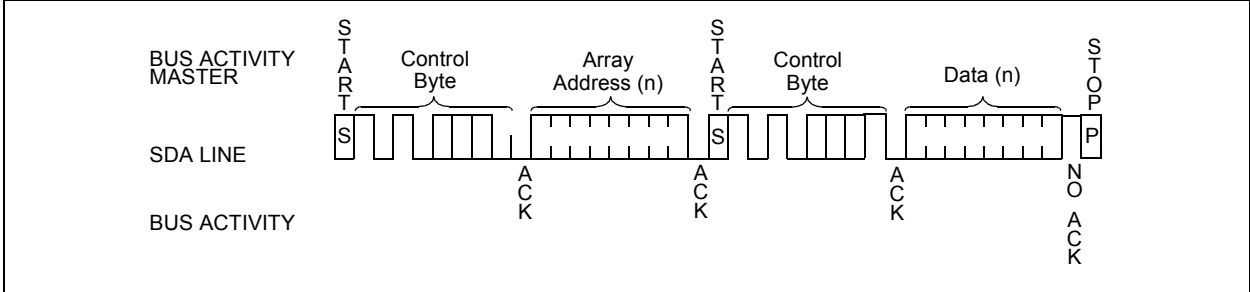
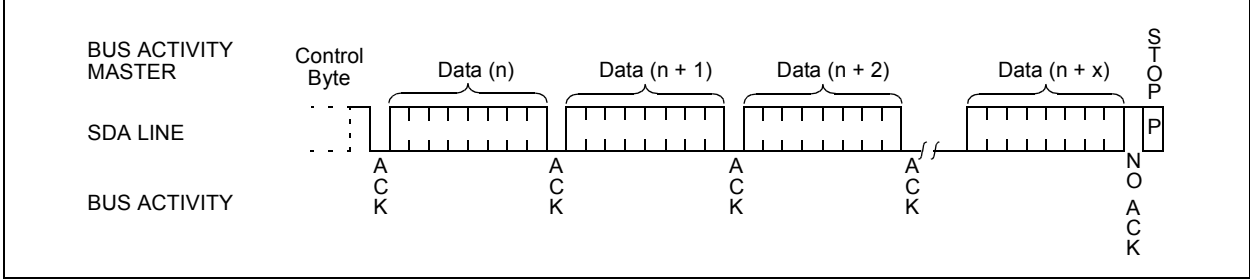


FIGURE 8-3: SEQUENTIAL READ



24AA044

9.0 PACKAGING INFORMATION

9.1 Package Marking Information

8-Lead PDIP (300 mil)



Example:



8-Lead SOIC (3.90 mm)



Example:



8-Lead TSSOP



Example:



8-Lead MSOP



Example:



8-Lead 2x3 UDFN



Example:



Part Number	1st Line Marking Codes				
	PDIP	SOIC	TSSOP	MSOP	UDFN
24AA024	24AA044	24AA044	AACL	4A44YY	CAD

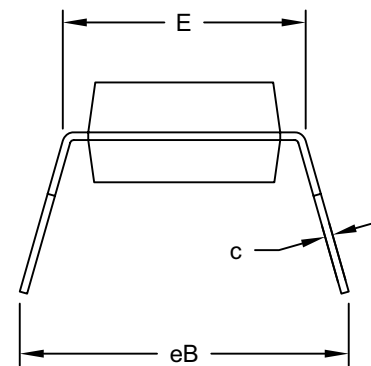
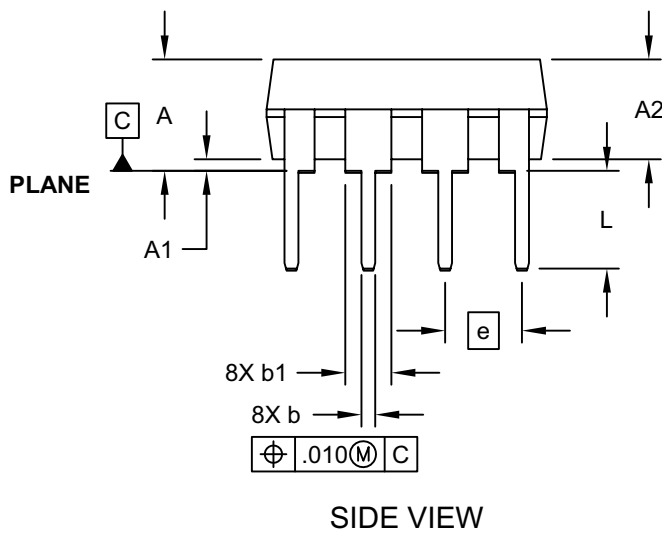
<p>Legend: XX...X Part number or part number code Y Year code (last digit of calendar year) YY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code (2 characters for small packages) Ⓔ3 JEDEC® designator for Matte Tin (Sn)</p>
<p>Note: For very small packages with no room for the Pb-free JEDEC designator Ⓔ3, the marking will only appear on the outer carton or reel label.</p>
<p>Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.</p>

*Standard OTP marking consists of Microchip part number, year code, week code, and traceability code.

24AA044

8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing No. C04-018D Sheet 1 of 2

8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	.100 BSC		
Top to Seating Plane	A	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing	§	eB	-	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-018D Sheet 2 of 2

24AA044

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing No. C04-057C Sheet 1 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	4.90 BSC		
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-057C Sheet 2 of 2

24AA044

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		1.27 BSC		
Contact Pad Spacing	C			5.40	
Contact Pad Width (X8)	X1				0.60
Contact Pad Length (X8)	Y1				1.55

Notes:

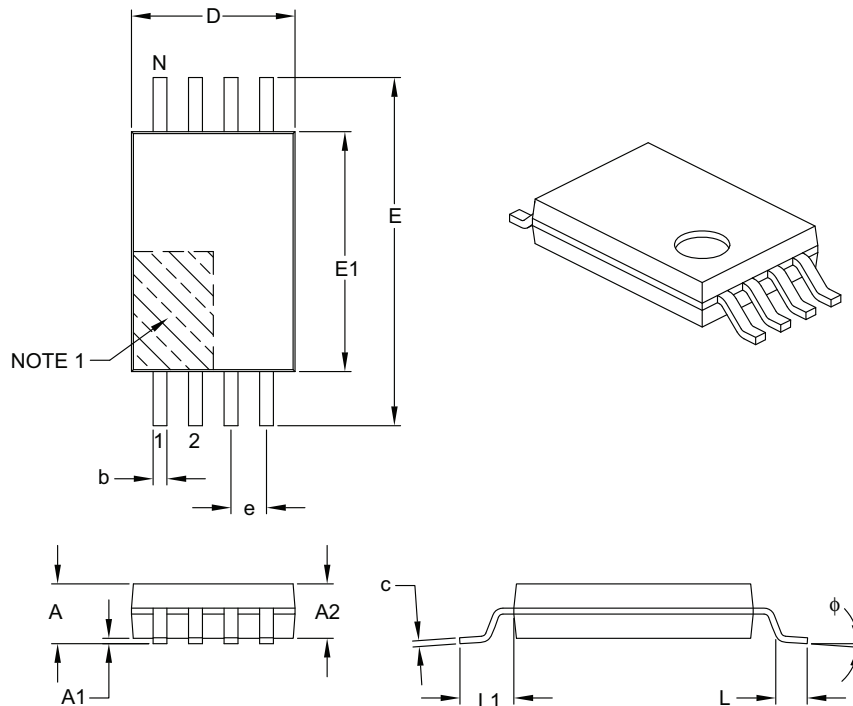
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	–	0.15
Overall Width	E	6.40 BSC		
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	2.90	3.00	3.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	–	8°
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.19	–	0.30

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-086B

24AA044

8-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C1		5.90	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.45
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension, Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2086A

8-Lead Plastic Micro Small Outline Package (MS) [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



8-Lead Plastic Micro Small Outline Package (MS) [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e	0.65 BSC		
Overall Height	A	-	-	1.10
Molded Package Thickness	A2	0.75	0.85	0.95
Standoff	A1	0.00	-	0.15
Overall Width	E	4.90 BSC		
Molded Package Width	E1	3.00 BSC		
Overall Length	D	3.00 BSC		
Foot Length	L	0.40	0.60	0.80
Footprint	L1	0.95 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.08	-	0.23
Lead Width	b	0.22	-	0.40

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-111C Sheet 2 of 2

8-Lead Plastic Micro Small Outline Package (MS) [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		MILLIMETERS		
Units		MIN	NOM	MAX
Dimension Limits				
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		4.40	
Overall Width	Z			5.85
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.45
Distance Between Pads	G1	2.95		
Distance Between Pads	GX	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

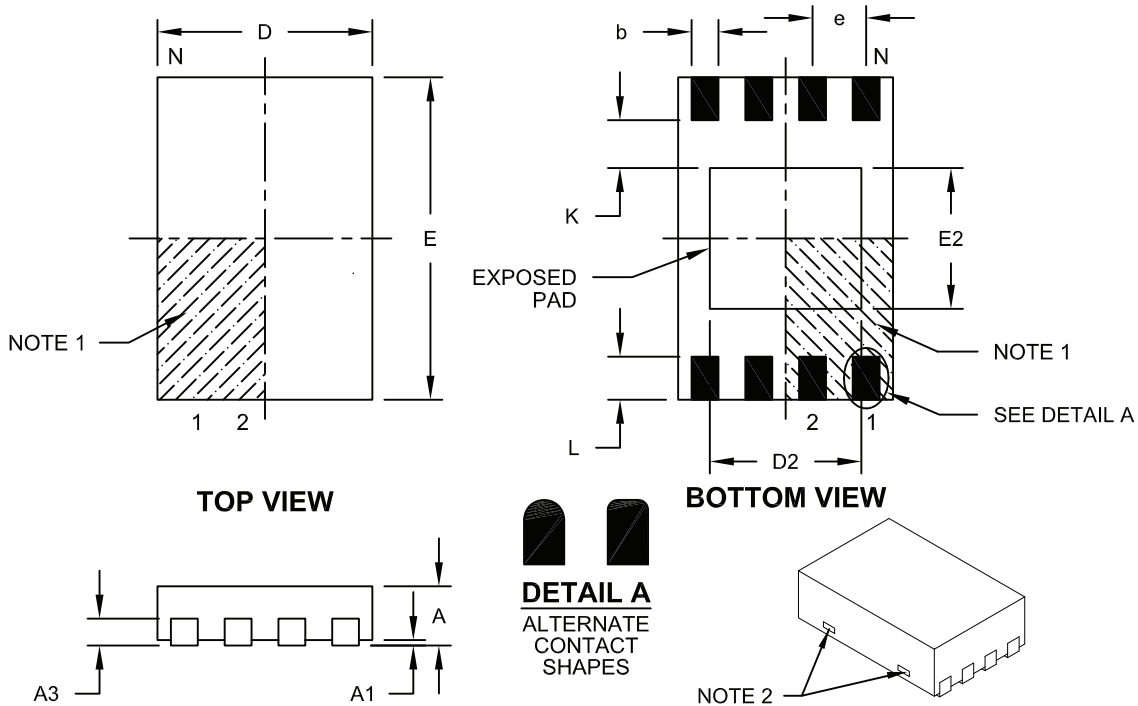
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2111A

24AA044

8-Lead Plastic Dual Flat, No Lead Package (MU) – 2x3x0.5 mm Body [UDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.50 BSC		
Overall Height	A	0.45	0.50	0.55
Standoff	A1			0.07
Contact Thickness	A3	0.127 REF		
Overall Length	D	1.95	2.00	2.05
Overall Width	E	2.95	3.00	3.05
Exposed Pad Length	D2	1.30	1.40	1.50
Exposed Pad Width	E2	1.20	1.30	1.40
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.25	0.30	0.35
Contact-to-Exposed Pad	K	0.55 REF		

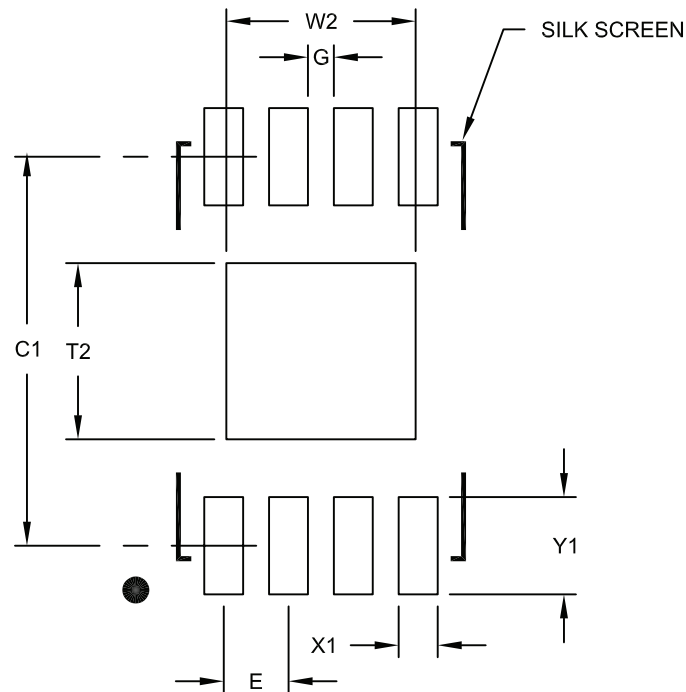
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-136B

8-Lead Plastic Dual Flat, No Lead Package (MU) – 2x3x0.5 mm Body [UDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	W2			1.46
Optional Center Pad Length	T2			1.36
Contact Pad Spacing	C1		3.00	
Contact Pad Width (X8)	X1			0.30
Contact Pad Length (X8)	Y1			0.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2136A

APPENDIX A: REVISION HISTORY

Revision A (04/2014)

Initial release of the document.

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or Field Application Engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: <http://microchip.com/support>

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>
Device	Temperature Range	Package
<p>Device: 24AA044: 1.7V, 4 Kbit Addressable Serial EEPROM. 24AA044T: 1.7V, 4 Kbit Addressable Serial EEPROM (Tape and Reel).</p> <p>Temperature Range: I = -40°C to +85°C E = -40°C to +125°C</p> <p>Package: P = Plastic DIP, (300 mil Body), 8-lead SN = Plastic SOIC, (3.90 mm Body) ST = TSSOP, 8-lead MS = MSOP, 8-lead MUY⁽¹⁾ = Plastic Dual Flat (UDFN), No lead package, 2x3 mm body, 8-lead</p>		
<p>Examples:</p> <ul style="list-style-type: none"> a) 24AA044-I/P: Industrial Temperature, 1.7V, PDIP Package b) 24AA044-I/SN: Industrial Temperature, 1.7V, SOIC Package c) 24AA044T-I/ST: Industrial Temperature, 1.7V, TSSOP Package, Tape and Reel d) 24AA044T-E/MUY: Automotive Temperature, 1.7V, UDFN Package, Tape and Reel e) 24AA044T-E/MS: Automotive Temperature, 1.7V, MSOP Package, Tape and Reel 		
<p>Note 1: "Y" indicates a Nickel Palladium Gold (NiPdAu) finish.</p>		

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rPIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MTP, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniclient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rFLAB, Select Mode, SQI, Serial Quad I/O, Total Endurance, TSHARC, UniWinDriver, WiperLock, ZENA and Z-Scale are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

GestIC and ULPP are registered trademarks of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2014, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

ISBN: 978-1-63276-162-0

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949 ==

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC[®] MCUs and dsPIC[®] DSCs, KEELOQ[®] code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



MICROCHIP

Worldwide Sales and Service

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://www.microchip.com/support>

Web Address:
www.microchip.com

Atlanta

Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Austin, TX

Tel: 512-257-3370

Boston

Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago

Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland

Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas

Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit

Novi, MI
Tel: 248-848-4000

Houston, TX

Tel: 281-894-5983

Indianapolis

Noblesville, IN
Tel: 317-773-8323
Fax: 317-773-5453

Los Angeles

Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

New York, NY

Tel: 631-435-6000

San Jose, CA

Tel: 408-735-9110

Canada - Toronto

Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon
Hong Kong
Tel: 852-2943-5100
Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8569-7000
Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Hangzhou

Tel: 86-571-8792-8115
Fax: 86-571-8792-8116

China - Hong Kong SAR

Tel: 852-2943-5100
Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8864-2200
Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-3019-1500

Japan - Osaka

Tel: 81-6-6152-7160
Fax: 81-6-6152-9310

Japan - Tokyo

Tel: 81-3-6880-3770
Fax: 81-3-6880-3771

Korea - Daegu

Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-5778-366
Fax: 886-3-5770-955

Taiwan - Kaohsiung

Tel: 886-7-213-7830

Taiwan - Taipei

Tel: 886-2-2508-8600
Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Dusseldorf

Tel: 49-2129-3766400

Germany - Munich

Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Germany - Pforzheim

Tel: 49-7231-424750

Italy - Milan

Tel: 39-0331-742611
Fax: 39-0331-466781

Italy - Venice

Tel: 39-049-7625286

Netherlands - Drunen

Tel: 31-416-690399
Fax: 31-416-690340

Poland - Warsaw

Tel: 48-22-3325737

Spain - Madrid

Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

Sweden - Stockholm

Tel: 46-8-5090-4654

UK - Wokingham

Tel: 44-118-921-5800
Fax: 44-118-921-5820

03/25/14

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru